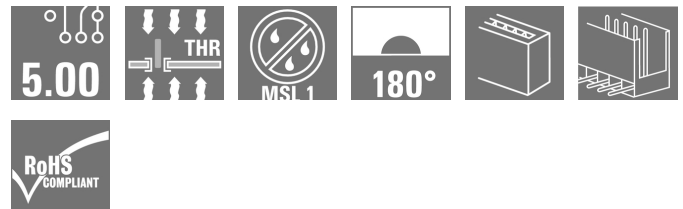


OMNIMATE Signal - series BL/SL 5.00
SL-SMT 5.00HC/04/180 3.2SN BK RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
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Fon: +49 5231 14-0
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High-temperature-resistant, straight, open pin header.
Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Type	SL-SMT 5.00HC/04/180 3.2SN BK RL
Order No.	2441070000
Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 5.00 mm, No. of poles: 4, 180°, Solder pin length (l): 3.2 mm, tinned, black, Tape
GTIN (EAN)	4050118455410
Qty.	250 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Tape

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Technical data
Dimensions and weights

Width	20 mm	Width (inches)	0.787 inch
Height	15.2 mm	Height (inches)	0.598 inch
Height of lowest version	12 mm	Depth	8.5 mm
Depth (inches)	0.335 inch	Net weight	1.837 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.00	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	180°
No. of poles	4	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	+0.1 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0.03 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		L1 in mm	15 mm
L1 in inches	0.591 inch	Pin series quantity	2
Can be coded	Yes	Plugging cycles	25
Plugging force/pole, max.	7 N	Pulling force/pole, max.	5.5 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
CTI	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
GWIT	930 °C	GWFI	960 °C
Contact material	CuMg	Contact surface	tinned
Layer structure of solder connection	1-3 µm Ni / 2-4 µm Sn matt	Layer structure of plug contact	1-3 µm Ni / 2-4 µm Sn matt
Storage temperature, min.	-25 °C	Storage temperature, max.	55 °C
Max. relative humidity during storage	80 %	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. no. of poles (Tu=20°C)	27.5 A
Rated current, max. no. of poles (Tu=20°C)	19 A	Rated current, min. no. of poles (Tu=40°C)	24 A
Rated current, max. no. of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	15 A	Rated current (Use group D / CSA)	15 A

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SL-SMT 5.00HC/04/180 3.2SN BK RL

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Technical data

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 18.5 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are
 maximum values, details -
 see approval certificate.

Packing

Packaging	Tape	VPE length	0 m
VPE width	0 m	VPE height	0 m
Tape depth (T2)	17.5 mm	Tape width (W)	56 mm
Tape pocket depth (K0)	17 mm	Tape pocket height (A0)	8.2 mm
Tape pocket width (B0)	43.12 mm	Tape pocket separation (P1)	16 mm
Tape hole separation (E)	1.75 mm	Tape pocket separation (F)	26.2 mm
Tape reel diameter Ø (A)	330 mm	Surface resistance	$R_s = 10^9 - 10^{12} \Omega$
Width Pick & Place Pad (W_{PPP})	9.6 mm	Length Pick & Place Pad (L_{PPP})	12.36 mm
Diameter of the withdrawal surface ($\varnothing D_{max}$)	8.5 mm	Protrusion 1 Pick & Place Pad ($L_{01 (PPP)}$)	2 mm
Protrusion 2 Pick & Place Pad ($P_{02 (PPP)}$)	2.3 mm		

Classifications

ETIM 4.0	EC002637	ETIM 5.0	EC002637
ETIM 6.0	EC002637	eClass 6.2	27-26-07-04
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02

Notes

Notes

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Approvals

Approvals



ROHS

Conform

Downloads

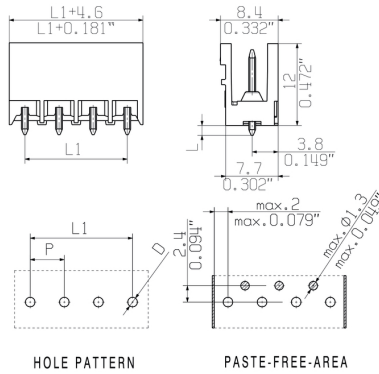
Brochure/Catalogue	FL DRIVES EN FL DRIVES DE
SMT white paper	Download Whitepaper

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Drawings

Dimensional drawing



Product benefits



Safe power transmission

Product benefits Proven properties

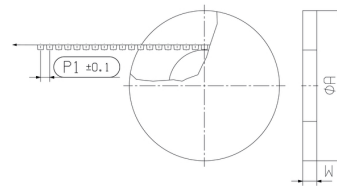


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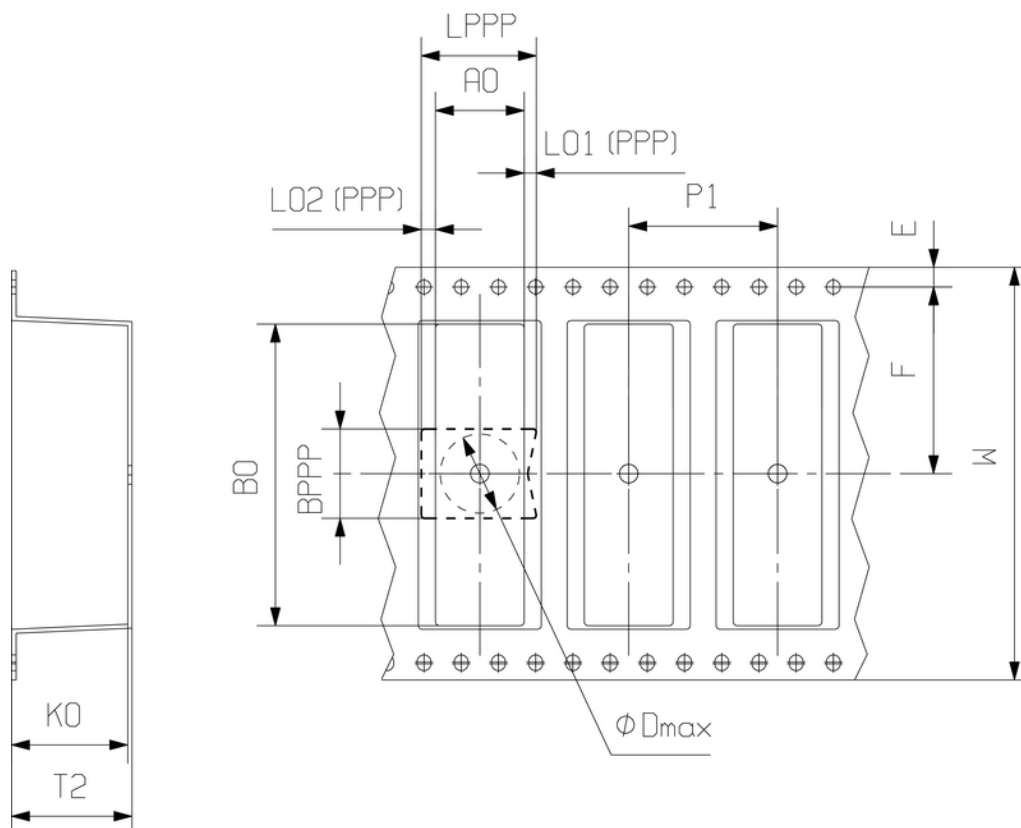
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Drawings

Dimensional drawing



Dimensional drawing



DIRECTION OF UNREELING →

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.